

USG layer 4 is between approximately 1,000 – 3,000 angstroms, and the thickness of the field oxide 2 is between approximately 3,000 – 6,000 angstroms.

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Please replace the paragraph beginning at page 4, line 19, with the following rewritten paragraph:

Referring to Figure 5, after the layer 38 is formed, the structure 1 then goes through the CMP process. In one embodiment, the layer 38 is polished until the BPSG layer 6 is exposed. In another embodiment, the polishing stops before the BPSG layer 38 is exposed. In yet another embodiment, the polishing endpoint is empirically determined using a test wafer (not shown). Alternatively, endpoint data provided by the manufacturer of the CMP equipment may be used. After the CMP, the combined thickness *y_k* of all layers, *i.e.*, measured from the bottom of the field oxide 2 to the top of the layer 38, is between approximately 8,000 to 15,000 angstroms. In one embodiment, *y_k* is approximately 13,000 angstroms. Thus, the layers 4 and 6 and the polished layer 38 together compose the PMD stack 20.

Please replace the paragraph beginning at page 5, line 1, with the following rewritten paragraph:

Referring to Figure 6, subsequent to the CMP, an optional redeposition layer 46 may be formed on the layer 38. In one embodiment, the layer 46 is formed from PE-TEOS, has a thickness of approximately 2,000 angstroms, and composes part of the PMD 20. In another embodiment, the layer 46 is formed from TEOS.

In the Claims:

Claims 2, 4, 26, and 27, have been amended.

For the Examiner's convenience, all of the claims currently pending are shown here in their entirety.